INTEGRATED CIRCUITS



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HILIP

SAA1300

The SAA1300 is for switching on and off the supply lines of various circuit parts via an I²C bus signal. Furthermore, it can be used to supply current for switching diodes in radio and television tuners. It contains 5 output stages, which are capable of supplying up to 85 mA in the ON state or sinking up to –100 μ A in the OFF state.

Current limiting and short-circuit protection are included. The output stages are driven by a shift register/latch combination which is loaded via data from the I^2C bus. A power-on reset of the latches ensures the OFF state of the output stages (OUT 2 to OUT 5) without data reception from the I^2C bus. A subaddressing system allows the connection of up to three circuits on the same I^2C bus lines; one of the outputs (OUT 1, pin 7) can also be used as an input to select the device via a simple internal A/D converter.





PACKAGE OUTLINE

9-lead SIL; plastic (SOT142); SOT142-1; 1996 September 05.

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PINNING

PIN NO.	SYMBOL	FUNCTION		
1	GND	ground		
2	V _P	positive supply		
3	OUT 5			
4	OUT 4	outouto		
5	OUT 3			
6	OUT 2			
7	OUT 1	output and subaddressing input		
8	SDA	serial data line	l ² C buc	
9	SCL	serial clock line		

I²C BUS INFORMATION

Address, first byte

0 1 0 0 0 A B 0 where,

Α	в	FUNCTION	CONDITION
0	0	general address	OUT 1 = output
0	1	OUT 1 = input	address accepted if $V_{OUT 1} = V_{OUT L}$ (LOW)
1	0	OUT 1 = input	address accepted if $V_{OUT 1} = V_{OUT H}$ (HIGH)
1	1	OUT 1 = input	address accepted if $V_{OUT 1} = V_{OUT M}$ (MEDIUM)

Data, second byte

OUT 5, OUT 4, OUT 3, OUT 2, OUT 1, X, X, X

The I/O output stage (OUT 1) is switched as an input stage after a power-on reset. It depends on the contents of the first data transmission whether the output stage is switched as an output or remains as an input.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Supply voltage	VP	max. 13,2	V
Input voltage range at SDA, SCL	VI	-0,5 to + 6,0	V
Input voltage range at OUT 1	VI	-0,5 to + 12,5	V
Output voltage range at OUT 1 to OUT 5	Vo	-0,5 to + 12,5	V
Input current at SDA, SCL	l _l	max. 20	mA
Input current at OUT 1	l _l	max. 20	mA
Total power dissipation	P _{tot}	max. 825	mW
Storage temperature range	T _{stg}	-40 to + 125	°C
Operating ambient temperature ranges	T _{amb}	-20 to + 80	°C

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CHARACTERISTICS

 $V_P = 8$ V; $T_{amb} = 24$ °C; unless otherwise specified

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply (pin 2)					
Supply voltage range	VP	4	8	12	V
Supply current					
5 outputs LOW	I _{PL}	5	10	15	mA
5 outputs HIGH	I _{PH}	30	50	70	mA
Power on reset level output stage in "OFF" condition	V _{PR}	-	3,5	3,8	V
Maximum power dissipation ⁽¹⁾	P _{max}	-	650	-	mW
Inputs SDA, SCL (pins 8 and 9)					
Input voltage HIGH	VIH	3,0	-	5,5	V
Input voltage LOW	VIL	0	-	1,5	V
Input current HIGH	-I _{IH}	-	-	10	μA
Input current LOW	Іін	-	-	0,4	μA
Acknowledge sink current	I _{ACK}	2,5	-	-	mA
Maximum input frequency	f _{i max}	100	-	-	kHz
Outputs OUT 1 to OUT 5 (pins 3 to 7)					
Maximum output current; source: "ON"	I _{Oso}	+85	-	+150	mA
Maximum output current; source: "ON"					
T _{amb} = 80 °C	I _{Oso}	60	-	-	mA
Output voltage HIGH					
at I _{Oso} = 85 mA	V _{OH}	V _p -2	-	-	V
Output current; sink "OFF"	I _{Osi}	-100	-300	-	μA
Output voltage LOW					
at I _{Osi} = -100 μA	V _{OL}	-	-	100	mV
Output voltage MEDIUM					
at $I_0 = 10 \text{ mA}$	V _{OM}	V _P 0,5	-	-	V
OUT 1 used as subaddressing input					
Input voltage HIGH (code 1 0)	V _{OUT 1H}	0,72 V _P	-	VP	V
Input voltage MEDIUM (code 1 1)	V _{OUT 1M}	0,39 V _P	-	0,61 V _P	V
Input voltage LOW (code 0 1)	V _{OUT 1L}	0	-	0,28 V _P	V

Note

1. Outputs must not be driven simultaneously at maximum source current.

PACKAGE OUTLINE

SIL9MP: plastic single in-line medium power package; 9 leads



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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact

with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\,max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.		
Application information		
Where application information	on is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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